

#### **Features**

- Superior circuit protection
- Overcurrent and overvoltage protection
- Blocks surges up to rated limits
- High speed performance
- Small SMT package
- Agency recognition: 📢

### **Applications**

- Voice / VDSL cards
- Protection modules and dongles
- Process control equipment
- Test and measurement equipment
- General electronics

# TBU-CA Series - TBU® High Speed Protectors

#### **General Information**

The TBU-CA Series of Bourns® TBU® Line I products are low capacitance single bidirectional high speed protection components, constructed using MOSFET semiconductor technology, and designed to protect against faults caused by short circuits, AC power cross, induction and lightning surges.

Line In/ Line Out Line In TBU® Device Agency Approval

Description
UL File Number: E315805

The TBU® high speed protector placed in the system circuit will monitor the current with the MOSFET detection circuit triggering to provide an effective barrier behind which sensitive electronics will not be exposed to large voltages or currents during surge events. The TBU® device is provided in a surface mount DFN package and meets industry standard requirements such as RoHS and Pb Free solder reflow profiles.

#### Absolute Maximum Ratings (@ T<sub>A</sub> = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Part Number	Value	Unit
		TBU-CA025-xxx-WH	250	
V <sub>imp</sub>		TBU-CA040-xxx-WH	400	
	Peak impulse voltage withstand with duration less than 10 ms	TBU-CA050-xxx-WH	500	V
		TBU-CA065-xxx-WH	650	
		TBU-CA085-xxx-WH	850	
		TBU-CA025-xxx-WH	100	
	Continuous A.C. RMS voltage	TBU-CA040-xxx-WH	200	
V <sub>rms</sub>		TBU-CA050-xxx-WH	250	V
		TBU-CA065-xxx-WH	300	
		TBU-CA085-xxx-WH	425	
T <sub>op</sub>	Operating temperature range	-40 to +125	°C	
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C	
T <sub>imax</sub>	Maximum Junction Temperature	+125	°C	
ESD	HBM ESD protection per IEC 61000-4-2	±2	kV	

## **BOURNS**®

**Asia-Pacific:** Tel: +886-2 2562-4117 ● Fax: +886-2 2562-4116

**Europe:** Tel: +41-41 768 5555 • Fax: +41-41 768 5510

The Americas: Tel: +1-951 781-5500 • Fax: +1-951 781-5700

www.bourns.com

### **BOURNS**

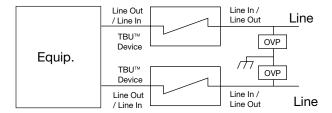
### Electrical Characteristics (@ $T_A$ = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Part Num	ber	Min.	Тур.	Max.	Unit
l <sub>trigger</sub>	Current required for the device to go from operating protected state	xx-050-WH xx-100-WH xx-200-WH xx-300-WH xx-500-WH	50 100 200 300 500	75 150 300 450 750	100 200 400 600 1000	mA	
R <sub>TBU</sub>	Vimp = 250 V   Itrigger (min.)   Vimp = 400 V   Itrigger (min.)   Vimp = 500 V   Itrigger (min.)   Vimp = 650 V   Itrigger (min.)   Vimp = 850 V   Itrigger (min.)	= 100 mA	25-050-WH 25-100-WH 25-100-WH 25-200-WH 25-300-WH 40-050-WH 40-100-WH 40-200-WH 40-300-WH 40-500-WH 50-050-WH 50-200-WH 50-300-WH 50-500-WH 65-100-WH 65-200-WH 65-200-WH 65-300-WH 65-300-WH 65-300-WH 65-300-WH 65-300-WH 65-300-WH 65-300-WH 65-300-WH 65-300-WH 65-300-WH 65-300-WH 65-300-WH 65-300-WH 65-300-WH 65-300-WH		13.3 7.1 4.2 3.2 2.6 14.3 8.1 5.2 4.3 3.6 15.7 9.5 6.6 5.0 17.7 11.5 8.6 7.0 21.4 15.2 12.3 11.3	15.3 8.2 4.8 3.8 3.0 16.5 9.4 6.0 5.0 4.2 18.0 10.9 7.5 6.5 5.7 20.3 13.2 9.8 8.8 8.0 24.5 17.4 14.0 13.0	Ω
t <sub>block</sub>	V <sub>imp</sub> = 850 V I <sub>trigger</sub> (min.)  Time for the device to go from normal operating sta		85-500-WH		10.7	12.2	μs
IQ	Current through the triggered TBU® device with 50		0.25	0.50	1.00	mA	
V <sub>reset</sub>	Voltage below which the triggered TBU® device will	erating state	12	16	20	V	
R <sub>th(j-l)</sub>	Junction to package pads - FR4 using recommend			98		°C/W	
R <sub>th(j-l)</sub>	Junction to package pads - FR4 using heat sink on			40		°C/W	

### BOURNS

#### **Reference Application**

The TBU® devices are general use protectors used in a wide variety of applications. The maximum voltage rating of the TBU® device should never be exceeded. Where necessary, an OVP should be employed to limit the maximum voltage. A cost-effective protection solution combines Bourns® TBU® protection devices with a pair of Bourns® MOVs. For bandwidth sensitive applications, a Bourns® GDT may be substituted for the MOV.



#### **Basic TBU Operation**

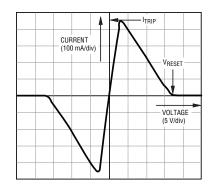
The TBU® device, constructed using MOSFET semiconductor technology, placed in the system circuit will monitor the current with the MOSFET detection circuit triggering to provide an effective barrier behind which sensitive electronics are not exposed to large voltages or currents during surge events. The TBU® device operates in approximately 1 µs - once line current exceeds the TBU® device's trigger current Itrigger. When operated, the TBU® device restricts line current to less than 1 mA typically. When operated, the TBU® device will block all voltages including the surge up to rated limits.

After the surge, the TBU® device resets when the voltage across the TBU® device falls to the  $V_{reset}$  level. The TBU® device will automatically reset on lines which have no DC bias or have DC bias below  $V_{reset}$  (such as unpowered signal lines).

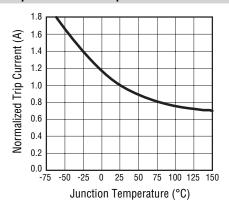
If the line has a normal DC bias above V<sub>reset</sub>, the voltage across the TBU® device may not fall below V<sub>reset</sub> after the surge. In such cases, special care needs to be taken to ensure that the TBU® device will reset, with software monitoring as one method used to accomplish this. Bourns application engineers can provide further assistance.

#### **Performance Graphs**

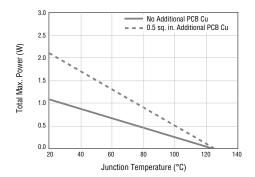
#### Typical V-I Characteristics (TBU-CA050-300-WH)



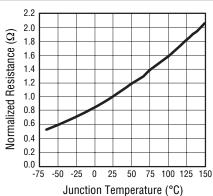
#### **Typical Trip Current vs. Temperature**



#### **Power Derating Curve**



#### Typical Resistance vs. Temperature

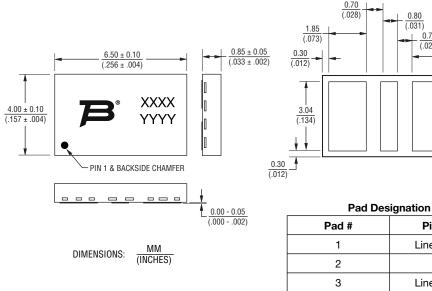


Specifications are subject to change without notice. Customers should verify actual device performance in their specific applications.

1.85

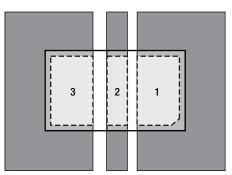
C  $\frac{0.25}{(.010)}$  PIN 1

#### **Product Dimensions**



#### **Recommended Pad Layout**

TBU® protectors have matte-tin termination finish. The suggested layout should use Non-Solder Mask Define (NSMD). The recommended stencil thickness is 0.10-0.12 mm (.004-.005 in.) with a stencil opening size 0.025 mm (.0010 in.) less than the device pad size. As when heat sinking any power device, it is recommended that wherever possible, extra PCB copper area is allowed. For minimum parasitic capacitance, do not allow any signal, ground or power signals beneath any of the pads of the device.

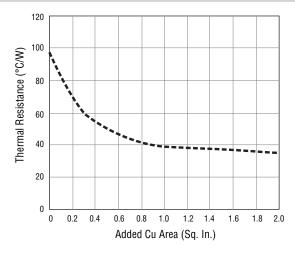


Dark grey areas show added PCB copper area for better thermal resistance.

Pad #	Pin Out				
1	Line In/Out				
2	NU				
3	Line Out/In				

#### Thermal Resistance vs Additional PCB Cu Area

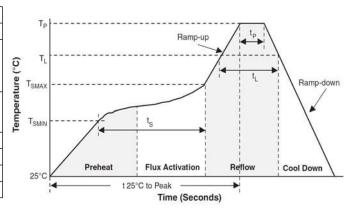
(.031) 0.70



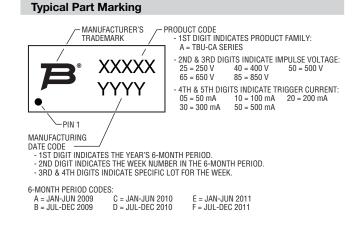
### **BOURNS**®

#### **Reflow Profile**

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Tsmax to Tp)	3 °C/sec. max.
Preheat - Temperature Min. (Tsmin) - Temperature Max. (Tsmax) - Time (tsmin to tsmax)	150 °C 200 °C 60-180 sec.
Time maintained above: - Temperature (TL) - Time (tL)	217 °C 60-150 sec.
Peak/Classification Temperature (Tp)	260 °C
Time within 5 °C of Actual Peak Temp. (tp)	20-40 sec.
Ramp-Down Rate	6 °C/sec. max.
Time 25 °C to Peak Temperature	8 min. max.

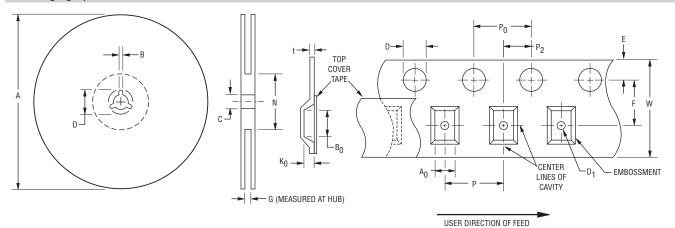


#### **How to Order** TBU - CA 085 - 500 - WH TBU® Product CA = Bi-Series Impulse Voltage Rating 025 = 250 V 040 = 400 V050 = 500 V065 = 650 V 085 = 850 V Trigger Current 050 = 50 mA 100 = 100 mA 200 = 200 mA 300 = 300 mA500 = 500 mAHold to Trip Ratio Suffix W = Hold to Trip Ratio Package Suffix -H = DFN Package



### BOURNS

#### **Packaging Specifications**



QUANTITY: 3000 PIECES PER REEL

Α		E	В		С		D		N
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Ref.	Ref.
326	330	1.5	2.5 (.098)	12.8	13.5	20.2	_	16.5	102
(12.835)	(13.002)	(.059)	(.098)	(.504)	(.531)	(.795)		(.650)	(4.016)

Α0		В0		D		D1		E		F	
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	max.
4.3 (.169)	4.5 (.177)	6.7 (.264)	6.9 (.272)	1.5 (.059)	1.6 (.063)	1.5 (.059)	-	1.65 (.065)	1.85 (.073)	7.4 (.291)	7.6 (.299)
K <sub>0</sub>		F	•	P <sub>0</sub>		P2		t		W	
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
1.0 (.039)	1.2 (.047)	7.9 (.311)	8.1 (.319)	3.9 (.159)	4.1 (.161)	1.9 (.075)	2.1 (.083)	0.25 (.010)	0.35 (.014)	15.7 (.618)	16.3 (.642)

DIMENSIONS:  $\frac{MM}{(INCHES)}$